

**Features**

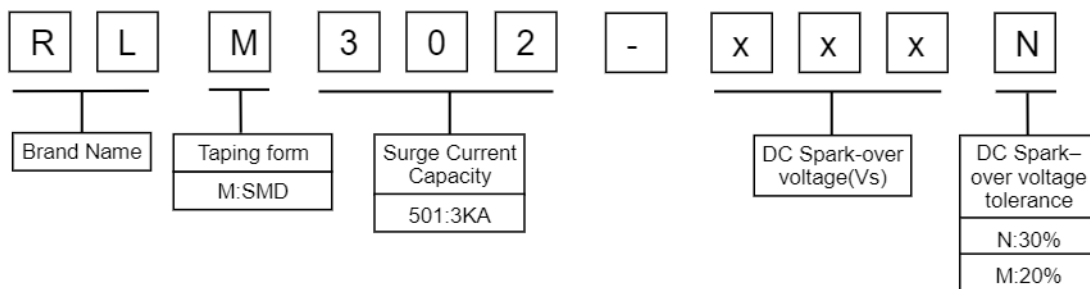
- RoHS compliant.
- Bilateral symmetrical.
- Less decay at on/off state.
- Approximately zero leaking current before clamping voltage
- High capability to withstand repeated lightning strikes.
- Low electrode capacitance( $\leq 1.0\text{pF}$ ) and high isolation ( $\geq 100\text{M}\Omega$ ).
- Temperature, humidity and lightness insensitive.
- Working temperature range: :  $-45^{\circ}\text{C} \sim +85^{\circ}\text{C}$
- Storing temperature range:  $-45^{\circ}\text{C} \sim +85^{\circ}\text{C}$



**Applications**

- Power Supplies
- Motor sparks eliminating
- Relay switching spark absorbing
- Data line pulse guarding
- Telephone/Fax/Modem
- High frequency signal transmitters/receivers
- Satellite antenna
- Radio amplifiers
- Alarm systems
- Cathode ray tubes in Monitors/Television Viewing Systems

**Part Number Code**



**Electrical Characteristics**

Type Number	DC Spark-Over Voltage	Min. Insulation Resistance		Max. Capacitance (1kHz-6Vmax. )	Surge Current Capacity	Surge Life Test
	Vs	Test Voltage	I <sub>R</sub>	C <sub>j</sub>	8/20μs	
	V	V	MΩ	pF	A	
RLM302-141N	140±30%	50	100	1	3000	1kHz-10KV Max (10X700 μ sec-6000V 150A 10 time)
RLM302-181N	180±30%	50	100	1	3000	
RLM302-201M	200±20%	100	100	1	3000	
RLM302-301M	300±20%	100	100	1	3000	
RLM302-401M	400±20%	250	100	1	3000	
RLM302-501M	500±20%	250	100	1	3000	

**Recommended Soldering Conditions**

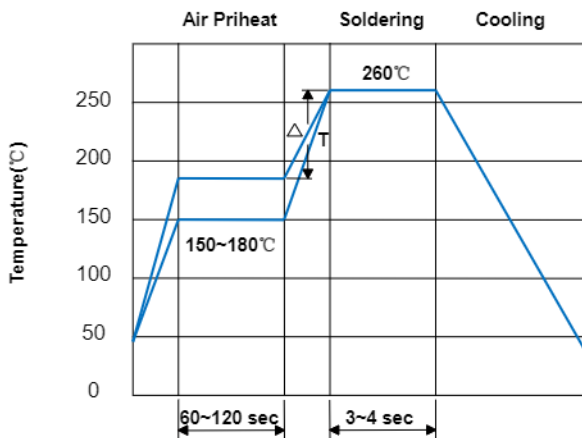
**Flow Soldering Conditions**

**Hand Soldering**

Solder iron temperature: 350±5℃  
Heating time: 3 seconds max.

**General attention to soldering**

- 1.High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- 2.For soldering, please refer to the soldering curves above. However, please keep exposures to temperatures exceeding 200℃ to fewer than 50 seconds.
- 3.Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.



- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 110℃
- 3) After soldering, do not force cool, allow the parts to cool gradually.

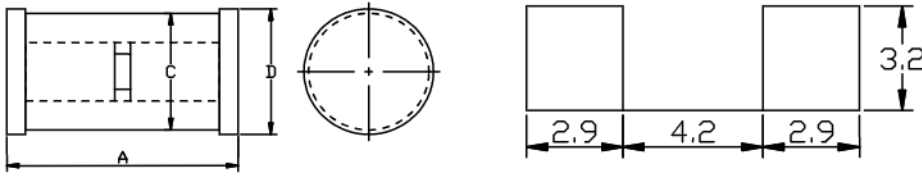
**Cleaning**

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

- Frequency: 40kHz max.
- Output power: 20W/liter
- Cleaning time: 5 minutes max.

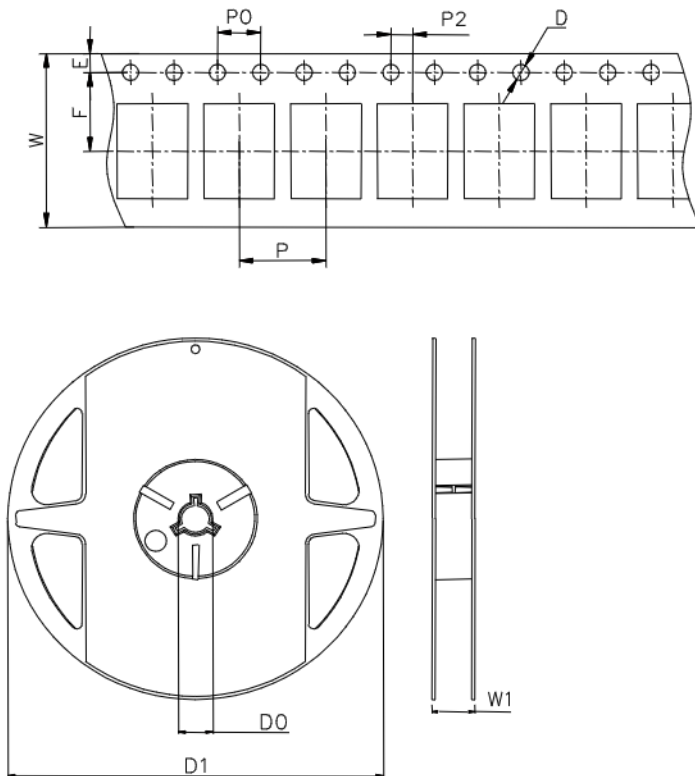


Dimensions & Recommended Pad Size(mm)



DIM	Millimeters	Inches
A	6.0±0.5	0.236±0.02
C	Φ3.1±0.5	0.122±0.02
D	Φ3.3±0.5	0.13±0.02

Taping and Reel Specifications



Symbol	Millimeters	Inches
W	16±0.2	0.630±0.008
P	8±0.1	0.314±0.004
F	7.5±0.05	0.295±0.002
E	1.75±0.1	0.069±0.004
D	1.5±0.1	0.059±0.004
P0	4±0.1	0.157±0.004
P2	2±0.1	0.079±0.004
D0	13±0.15	0.512±0.006
D1	330±2	12.992±0.079
W1	20±0.2	0.787±0.008

Quantity:2000PCS Per Reel

